

ABSTRACT OF DISCLOSURE

A process for manufacturing an integrated circuit package includes forming a plurality of solder balls on a first surface of a substrate and mounting a semiconductor die to the substrate such that bumps of the semiconductor die are electrically connected to conductive traces of the substrate. The semiconductor die and the solder balls are encapsulated in an overmold material on the substrate such that portions of the solder balls are exposed. A ball grid array is formed such that bumps of the ball grid array are electrically connected to the conductive traces and the integrated circuit package is singulated.